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EXAMINER	
DURNFORD GESZVAI, DILLON	

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2622	

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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	10/784,102	KALE ET AL.	
	Examiner	Art Unit	
	Dillon Durnford-Geszvain	2622	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☒ Responsive to communication(s) filed on *17 September 2009*.

2a)☒ This action is **FINAL**. 2b)☐ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *1-3,5,7-14,16-24,26-35,37-48,50,51,54,61,62,65,67,68 and 71-81* is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☒ Claim(s) *1-3,5,7-14,16-24,26-35,37-48,50,51,54,61,62,65,67,68,71-73,75,77,78,80 and 81* is/are rejected.

7)☒ Claim(s) *74,76 and 79* is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☐ The drawing(s) filed on _____ is/are: a)☐ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☐ All b)☐ Some * c)☐ None of:

1.☐ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1)☒ Notice of References Cited (PTO-892)

2)☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)

3)☐ Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date _____.

4)☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.

5)☐ Notice of Informal Patent Application

6)☐ Other: _____.

DETAILED ACTION

Response to Amendment

1. Claims **1-3, 5, 7-14, 16-24, 26-35, 37-48, 50, 51, 54, 61, 62, 65, 67, 68** and **71-81** are pending, claims **1, 9, 17, 21, 27, 39** and **65** are amended, claims **71-81** are newly added, and claims **4, 6, 15, 25, 36, 49, 52, 53, 55-60, 63, 64, 66, 69** and **70** are cancelled.

Response to Arguments

Applicant's arguments, see Remarks and amendments to the claims, filed 9/17/2009, with respect to the rejection(s) of the claim(s) under paragraph 112 have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of US 6,798,031 (Honda).

Claim Objections

2. Claim **81** is objected to because of the following informalities: "the lens assembly" and "said lens" lack antecedent basis. This could be corrected by amending the claim to depend from claim **80**. Appropriate correction is required.

Claim Rejections - 35 USC § 102

3. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

4. **Claims 1-3, 5, 7-18, 20, 21, 23, 24, 26-28, 30-35, 37-41, 46-48, 50, 54, 61, 67, 68, 71-73, 77, 80 and 81 are rejected under 35 U.S.C. 102(e) as being anticipated by US 6,798,031 (Honda).**

5. As to claim **1**, Honda teaches a camera module apparatus, comprising:

a camera integrated circuit chip (comprising 10A and 12, see Fig. 5);

a lens 3; and

a molding 14A made on the camera integrated circuit chip for holding the lens 3 such that the lens 3 is positioned in relation to the camera integrated circuit chip by the molding (C13 L62-67), the molding defining a recess (the first setback portion in Fig. 5) and a spacer (the part of the molding 14A that is below the first setback portion in Fig. 5), the recess for receiving the lens (see Fig. 5 and note that the lens is placed in the recessed portion) and the spacer located adjacent a top surface of the camera integrated circuit chip and separating the lens and the camera integrated circuit chip (Fig. 5 and note that the part of 14A below the first setback portion is adjacent to the integrated circuit 10A and 12, and separates it from the lens, because the lens is supported by the spacer above the camera integrated circuit chip).

6. As to claim **2**, see the rejection of claim **1** and note that Honda further teaches the camera module of claim **1**, wherein:

the camera integrated circuit chip is mounted on a printed circuit board (see Fig. 5).

7. As to claim **3**, see the rejection of claim **1** and note that Honda further teaches the camera module apparatus of claim **1**, further comprising:

a protective cover 5 over the integrated circuit chip (see Fig. 5).

8. As to claim **5**, see the rejection of claim **3** and note that Honda further teaches the camera module apparatus of claim **3**, wherein: the protective member is a glass sheet 5 (see Fig. 5).

9. As to claim **7**, see the rejection of claim **1** and note that Honda further teaches the camera module apparatus of claim **1**, wherein: the lens 3 is held in place on the molding 14A by an adhesive 24 (C13 L1-6).

10. As to claim **8**, see the rejection of claim **1** and note that Honda teaches the Camera module apparatus of claim **1**, wherein: the spacer positions the lens relative to the camera integrated circuit chip (Fig. 5).

11. As to claim **9** Honda teaches an integrated camera circuit and lens module, comprising:

a camera integrated circuit chip (comprising 10A and 12);

a holder 14A made at least partially on the camera integrated circuit (C13 L62-67) the holder defining a spacer (the part of the holder 14A that is below the first setback portion in Fig. 5) located adjacent a top surface of the camera integrated circuit,

the spacer separating the lens assembly and the camera integrated circuit (Fig. 5); and

wherein the lens assembly is affixed to the camera integrated circuit via the holder 14A, the holder enabling the insertion of the lens assemble into the holder, thereby positioning the lens assembly with respect to the camera integrated circuit (see Fig. 5).

12. As to claim **10**, see the rejection of claim **9**, and note that Honda further teaches the integrated camera circuit and lens module of claim **9**, wherein:

the lens assembly (3 and 22) is rigidly affixed to the camera integrated circuit via the holder 14A; and

the spacer causes a gap between at least a portion of the lens assembly and a sensor array of the camera integrated circuit (Fig. 5).

13. As to claim **11**, see the rejection of claim **9** and note that Honda further teaches the integrated circuit and lens module of claim **9**, wherein: the holder 14A is a molded component (C13 L62-67).

14. As to claim **12**, see the rejection of claim **11** and note that Honda further teaches the integrated circuit and lens module of claim **11**, wherein: the lens assembly (3 and 22) is attached to the holder 14A by an adhesive 24 (C13 L1-6).

15. As to claim **13**, see the rejection of claim **9** and note that Honda further teaches the integrated camera circuit and lens module of claim **9**, wherein: the camera integrated circuit is mounted on a circuit board (Fig. 5).

16. As to claim **14**, see the rejection of claim **9** and note that Honda further teaches the integrated camera circuit and lens module of claim **9**, further comprising:

a protective cover 5 held in place over the camera integrated circuit chip by the holder (Fig. 5).

17. As to claim **16**, see the rejection of claim **14** and note that Honda further teaches the integrated camera circuit and lens module of claim **14**, wherein: the protective member is a glass sheet 5 (see Fig. 5).

18. As to claim **17**, Honda teaches a method for producing a camera module, comprising:

molding a receptacle 14A over an integrated circuit such that the receptacle is capable of receiving a lens assembly (3 and 22) and positioning the lens assembly with respect to the integrated circuit (C13 L62-67), the receptacle defining a spacer (the part of the receptacle 14A that is below the first setback portion in Fig. 5) capable of separating the lens assembly and the integrated circuit, the spacer located adjacent a top surface of the integrated circuit (Fig. 5);

inserting the lens assembly (3 and 22) into the receptacle; and

securing the lens assembly into the receptacle 14A (via adhesive 24, C13 L1-6).

19. As to claim **18**, see the rejection of claim **17** and note that Honda further teaches the method of claim **17**, wherein:

the lens assembly is secured by an adhesive 24 (C13 L1-6).

20. As to claim **20**, see the rejection of claim **17** and note that Honda further teaches the method of claim **17**, wherein: the receptacle 14A includes a recessed portion for receiving the lens assembly (Fig. 5).

21. As to claim **21**, see the rejection of claim **20** and note that Honda further teaches the method of claim **20**, wherein: the spacer is a projection that fixes the distance of the lens assembly (3 and 22) from the integrated circuit (Fig. 5).

22. As to claim **23**, see the rejection of claim **17** and note that Honda further teaches the method of claim **17**, further comprising:

placing a protective cover over the integrated circuit (See Fig. 5).

23. As to claim **24**, see the rejection of claim **23**, and note that Honda further teaches the method of claim **23**, wherein: the placing of the protective cover over the integrated circuit occurs during molding of the receptacle over the integrated circuit (14A is

interpreted as a protective cover and therefore it is placed during its molding).

24. As to claim **26**, see the rejection of claim **23** and note that Honda further teaches the method of claim **23**, wherein: the protective cover is a glass plate 5 (Fig. 5).

25. As to claim **27**, Honda teaches a camera apparatus, comprising:

an integrated circuit camera apparatus (10A and 12a, Fig. 5) having thereon a photosensitive array (10A);

a lens assembly (3 and 22) for focusing light on the photosensitive array 10A (Fig. 5); and

a spacer separating the lens assembly and the integrated circuit camera apparatus (the part of the receiving apparatus 14A that is below the first setback portion in Fig. 5); and wherein

the lens assembly (3 and 22) is positioned and rigidly affixed on the integrated circuit camera apparatus by a lens assembly receiving apparatus 14A made integrally on the integrated circuit camera apparatus (C13 L62-67); and

the spacer is an integral portion of the lens assembly receiving apparatus 14A, the spacer located adjacent a top surface of the integrated circuit camera apparatus (Fig. 5).

26. As to claim **28**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the lens assembly has a housing 22 for receiving at least one lens 3.

27. As to claim **30**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the integrated circuit camera apparatus is connected to a circuit board 12.

28. As to claim **31**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the integrated circuit camera apparatus is affixed to a circuit board 12; and

the lens assembly receiving apparatus 14A is formed at least partially on the circuit board (see Fig. 5).

29. As to claim **32**, see the rejection of claim **31** and note that Honda further teaches the camera apparatus of claim **31**, wherein: the lens assembly receiving apparatus 14A is a molded receptacle (C13 L62-67).

30. As to claim **33**, see the rejection of claim **31** and note that Honda further teaches the camera apparatus of claim **31**, wherein: the lens assembly (3 and 22) is rigidly affixed within the lens assembly receiving apparatus 14A (Fig. 5).

31. As to claim **34**, see the rejection of claim **31** and note that Honda further teaches the camera apparatus of claim **31**, wherein: the lens assembly (3 and 22) is affixed

within the lens assembly receiving apparatus 14A by an adhesive 24 (Fig. 5).

32. As to claim **35**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, further comprising: a protective cover fixed between the integrated circuit camera apparatus and the lens assembly by the lens assembly receiving apparatus (see Fig. 5).

33. As to claim **37**, see the rejection of claim **35** and note that Honda further teaches the camera apparatus of claim **35**, wherein: the protective cover is a glass plate 5 (Fig. 5).

34. As to claim **38**, see the rejection of claim **35** and note that Honda further teaches the camera apparatus of claim **35**, wherein: the lens assembly receiving apparatus is an overmold formed over the integrated circuit camera apparatus (C13 L62-67 and Fig. 5).

35. As to claim **39**, Honda teaches a camera module apparatus, comprising:

a camera integrated circuit chip (10A and 12);

a lens 3; and

means for holding 14A the lens 3 such that the lens is positioned in relation to the integrated circuit chip by the means for holding the lens, the means for holding the lens including a component molded on the camera integrated circuit chip (Fig. 5 and C13 L62-67); and

wherein the component molded on the camera integrated circuit chip includes a means for separating the lens and the camera integrated circuit chip (the part of the means for holding 14A that is below the first setback portion in Fig. 5).

36. As to claim **40**, see the rejection of claim **17** and note that Honda further teaches the method of claim **17**, wherein: the molding of the receptacle 14A over the integrated circuit includes contacting a top surface of the integrated circuit with a mold insert (note that if the molding is carried out in a manner such as that taught in Honda then this step is inherent as the receptacle 14A does not cover the entire surface of the integrated circuit and therefore there must be some sort of mold insert contacting the integrated circuit as otherwise the integrated circuit would be entirely covered by the receptacle).

37. As to claim **41**, see the rejection of claim **40** and note that Honda further teaches the method of claim **40**, wherein: the mold insert includes a compliant surface to protect the integrated circuit (in light of the rejection of claim **40** there must be a surface that contacts the integrated circuit and therefore protects it during the molding; as to the surface being compliant, all surfaces are compliant to some degree).

38. As to claim **46**, see the rejection of claim **1** and note that Honda further teaches the camera module of claim **1**, wherein:

a top surface of the camera integrated circuit chip includes a sensor array 10; and

the molding is adhered to the top surface (see Fig. 5).

39. As to claim **47**, see the rejection of claim **9** and note that Honda further teaches the integrated camera circuit and lens module of claim **9**, wherein:

a top surface of the camera integrated circuit includes a sensor array 10; and

the holder is adhered to the top surface (see Fig. 5).

40. As to claim **48**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the photosensitive array 10A is on a top surface of the integrated circuit camera apparatus (see Fig. 5); and

the lens assembly receiving apparatus 14A is adhered to the top surface (see Fig. 5).

41. As to claim **50**, see the rejection of claim **1** and note that Honda further teaches the camera module apparatus of claim **1**, wherein:

the spacer fixes the distance between the lens and the camera integrated circuit chip (Fig. 5 and note that the distance is fixed when the lens is placed in the spacer at least in the sense that it is not adjustable).

42. As to claim **54**, see the rejection of claim **9** and note that Honda further teaches the integrated camera circuit and lens module of claim **9**, wherein:

the spacer fixes the distance between the lens and the camera integrated circuit chip (Fig. 5 and note that the distance is fixed when the lens is placed in the spacer at least in the sense that it is not adjustable).

43. As to claim **61**, see the rejection of claim **17** and note that Honda further teaches the method of claim **17**, wherein:

the spacer fixes the distance between the lens assembly and the integrated circuit (Fig. 5).

44. As to claim **67**, see the rejection of claim **27** and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the lens assembly receiving apparatus 14A is an overmold formed over the integrated circuit camera apparatus (C13 L62-67); and

the spacer is part of the lens assembly receiving apparatus (Fig. 5).

45. As to claim **68**, see the rejection of claim **27**, and note that Honda further teaches the camera apparatus of claim **27**, wherein:

the spacer fixes the distance between the lens assembly and the integrated circuit camera apparatus (Fig. 5).

46. As to claim **71**, Honda teaches a camera module apparatus, comprising:

a camera integrated circuit chip including a sensor array (10A and 12, Fig. 5);

a lens 3;

a molding 14A, made on the camera integrated circuit chip for holding the lens such that the lens is positioned in relation to the camera integrated circuit chip by the molding, the molding including a recess for receiving the lens (Fig. 5);

an optically clear spacer 5 located within the recess and adjacent a top surface of the camera integrated circuit chip, the spacer separating the lens and the camera integrated circuit chip when the lens is placed in the recess (Fig. 5 and note that the spacer 5 is between the chip and the lens).

47. As to claim **72**, see the rejection of claim **71** and note that Honda teaches the camera module apparatus of claim **71**, wherein:

the optically clear spacer 5 is a protective cover positioned over the sensor array (Fig. 5).

48. As to claim **73**, see the rejection of claim **72** and note that Honda further teaches the camera module of claim **72**, wherein:

the optically clear spacer is glass (Fig. 5).

49. As to claim **77**, see the rejection of claim **71** and note that Honda further teaches the camera module of claim **71**, wherein:

the camera integrated circuit is mounted on a printed circuit board (Fig. 5).

50. As to claim **80**, see the rejection of claim **71** and note that Honda further teaches the camera module of claim **71**, wherein:

the lens 3 is part of the lens assembly (Fig. 5).

51. As to claim **81**, see the rejection of claim **80** and note that Honda further teaches the camera module of claim **80**, wherein:

the lens assembly has a housing 22 for receiving said lens (Fig. 5).

Claim Rejections - 35 USC § 103

52. **Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 6,798,031 (Honda) in view of US 2002/0191103 (Akimoto).**

53. As to claim **19**, see the rejection of claim **17** and note that Honda may not teach that the integrated circuit is secured to a circuit board before the receptacle is molded over the integrated circuit. However, Akimoto teaches a method of producing a camera module (fig. 2) where an integrated circuit 2 is secured to a circuit board 5 before a receptacle 34 is placed over the integrated circuit. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have attached the integrated circuit of Honda from above the circuit board instead of from below as this would allow for the circuit board to be better protected and more securely attached.

54. **Claim 22 and 78 are rejected under 35 U.S.C. 103(a) as being unpatentable over US 6,798,031 (Honda) in view of US 7,009,654 (Kuno).**

55. As to claim **22**, see the rejection of claim **17** and note that Honda does not teach that the camera is attached to a flex circuit. However, Kuno teaches a camera module attached to a flex circuit (C5 L42-47). Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to have attached the camera module of Honda to a flex circuit as this would provide for a camera module that would be less likely to break.

56. Claim **78** contains a similar limitation to claim **22** but depends from claim **71** and is rejected for similar reasons to claim **22**.

57. **Claim 29 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 6,798,031 (Honda) in view of US Pre-Grant Publication 2004/0109079 (Fujimoto).**

58. As to claim **29**, see the rejection of claim **27** and note that what Honda doesn't teach is the lens assembly having a housing for receiving two lenses. However, Fujimoto teaches a lens assembly for an image sensor module that has a housing for receiving two lenses (see Fig. 1 and [0026]). Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to have made the housing of Honda in such a fashion so as to hold two lenses as is done in the invention of Fujimoto et al. as compared to the case where a single lens is used, the use of the two lenses of Fujimoto et al. can increase the number of apertures, prevent the

distortion of a captured image and provide a clear captured image.

59. **Claims 42-45 are rejected under 35 U.S.C. 103(a) as being unpatentable over US 6,798,031 (Honda) in view of US 7,199,438 (Appelt).**

60. As to claim **42**, see the rejection of claim **17** and note Honda does not teach molding receptacles or attaching receptacles over a plurality of integrated circuits simultaneously. However, Appelt teaches molding receptacles 430 over a plurality of integrated circuits simultaneously (see Column 1 line 65 to Column 2 line 2 and note that the method of Appelt may be carried out with the substrate in matrix array). Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to have molded receptacles over a plurality of integrated circuits as this would allow for mass production and would further reduce the cost of an optical semiconductor package.

61. As to claim **43**, see the rejection of claim **17** and note Honda does not teach molding receptacles or attaching receptacles when the integrated circuit is physically coupled to other integrated circuits. However, Appelt teaches molding receptacles 430 over a plurality of integrated circuits simultaneously (see Column 1 line 65 to Column 2 line 2 and note that the method of Appelt may be carried out with the substrate in matrix array). Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to have molded receptacles over a plurality of integrated circuits as this would allow for mass production and would further reduce the cost of an

optical semiconductor package.

62. As to claim **44**, see the rejection of claim **43** and note that this limitation is covered in the rejection of claim **43**.

63. As to claim **45**, see the rejection of claim **43** and note that Honda in view of Appelt further teaches the method of claim **43**, wherein: the integrated circuit and the other integrated circuits are physically coupled by being mounted on a unitary substrate (see Column 1 line 65 to Column 2 line 2 and note that the Examiner interprets the substrate in matrix array as the substrate being a unitary substrate); and

the integrated circuit and the other integrated circuits are subsequently separated by dividing the unitary substrate (note that this is inherent if they are assembled on a unitary substrate and they are then packaged separately).

64. **Claims 51, 62, 65 and 75 are rejected under 35 U.S.C. 103(a) as being unpatentable over US 6,798,031 (Honda) in view of US 6,476,417 (Honda hereinafter denoted as '417)**

65. Claims **51, 62** and **65**, all contain some variation of the limitation that the protective cover is retained between the spacer and the integrated circuit. Honda does not explicitly teach this limitation. However, '417 teaches a protective cover 32 located between a spacer 30 and a integrated circuit chip 14a. Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to have

moved the cover 5 of Honda below the spacer of Honda as this would yield a predictable result.

Honda in view of '417 would further teaches that the spacer retains the protective cover on the on the camera integrated circuit chip because the spacer would on the chip and retaining the spacer if you put the protective cover of Honda below the spacer of Honda as taught by '417.

66. As to claim **75**, see the rejection of claim **71** and note that Honda does not teach that the spacer is mounted before the molding is made. However, as '417 teaches that a spacer 30 could be placed beneath a holder. Therefore it would have been obviousto one of ordinary skill in the art at the time the invention was made to put the spacer 5 of Honda under the molding 14A yielding a predictable result of reducing the complexity of the molding step, and the only way to do this would be to place the spacer before the molding was made.

Allowable Subject Matter

67. Claims **74, 76** and **79** are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dillon Durnford-Geszvain whose telephone number is (571) 272-2829. The examiner can normally be reached on Monday through Friday 8 am to 5 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Dave Ometz can be reached on (571) 272-7593. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/DDG/ 1/8/2009

/David L. Ometz/
Supervisory Patent Examiner, Art Unit 2622